Claims:

1. (currently amended) A wafer lifting device comprising: ~~having~~

a wafer support member;

a lifting platform arranged under said a wafer support member; and

at least three pins; and

at least a pin guide body,

wherein the top side of said wafer support member includes a wafer bearing area, wherein said lifting platform is arranged to move vertically toward and away from the underside of the wafer support member, and wherein said at least three pins are arranged to be moved through ~~vertical through~~ vertical-through holes, which extend from the underside of the wafer support member to the wafer bearing area, by said lifting platform, said pins being moveable between a first upper position wherein said pins project from the wafer bearing area by a selected amount and a second lower position wherein said pins are retracted into said vertical-through ~~through~~ holes, wherein a separate pin guide body is provided for each pin, in which pin guide body the pin is guided and held for longitudinal movement, and wherein the pin guides body ~~are fixedly connected to~~ is detachably mounted on the wafer support member.

2. (currently amended) The wafer lifting device as claimed in claim 1, wherein the pin guide body has a guide hole in which the pin is arranged in movable fashion, and the pin guide body is arranged to hold the pin in said second lower position when the lifting platform is lowered.

3. (original) The wafer lifting device as claimed in claim 1 wherein the pin is mounted with spring-loading in the direction of said second lower position.

4. (currently amended) The wafer lifting device as claimed in claim 1 wherein the pin guide body is integrated with ~~in~~ the wafer support member and the through hole forms a guide hole for said pin.

5. (currently amended) The wafer lifting device as claimed in claim 1 wherein the pin guide body has a cylindrical body in which a guide hole is formed, and wherein said cylindrical body is mounted to the wafer support member.

6. (previously presented) The wafer lifting device as claimed in claim 5, wherein the cylindrical body is received in a mounting hole in the wafer support member, said mounting hole being coaxial with respect to the guide hole.

7. (previously presented) The wafer lifting device as claimed in claim 6, wherein the cylindrical body has a height corresponding to the thickness of the wafer support member and the mounting hole is a through hole having a diameter which is equal to or slightly greater than the diameter of the cylindrical body.

8. (original) The wafer lifting device as claimed in claim 6 wherein the mounting hole has an internal thread and the cylindrical body has an external thread and is arranged to be engaged by a tool and wherein the cylindrical body is screwed into the mounting hole.

9. (previously presented) The wafer lifting device as claimed in claim 5 wherein the cylindrical body, is provided with a flange at a side perpendicular to an axis of the guide hole, wherein said flange has mounting holes for receiving screws for connection to the wafer support member.

10. (previously presented) The wafer lifting device as claimed in claim 9, wherein the wafer support member is provided with threaded holes corresponding to said mounting holes.

11. (previously presented) The wafer lifting device as claimed in claims 9, wherein threaded bolts are mounted on the wafer support member and received through the mounting holes.

12. (original) The wafer lifting device as claimed in claim 5 wherein an enlarged bore having an upper and a lower end and having a larger cross section than the guide hole is arranged in the cylindrical body, said enlarged bore being coaxial with respect to the guide hole, wherein the pin has an attachment, which is smaller than the cross section of the enlarged bore and can be moved longitudinally therein together with the pin, and wherein the lower end of the enlarged bore is formed by a cover attached to the flange plate, said cover having a pin hole, which has a smaller cross section than the enlarged bore and through which the pin penetrates.

13. (original) The wafer lifting device as claimed in claim 12, wherein the attachment is designed as a ring surrounding the pin.

14. (original) The wafer lifting device as claimed in claim 12, wherein a helical spring surrounds the pin in the enlarged bore, said helical spring being retained between the upper end of the enlarged bore and the attachment.

15. (original) The wafer lifting device as claimed in claim 14, wherein the helical spring is composed of a material having a spring durability of greater than 250°C.

16. (original) The wafer lifting device as claimed in claim 15, wherein the material has a spring durability of up to 800°C.

17. (Currently Amended) A wafer lifting device comprising: ~~having~~

a wafer support member;

a lifting platform arranged under said a wafer support member; and

at least three pins; and

at least a pin guide body,

wherein the top side of said wafer support member includes a wafer bearing area,

wherein said lifting platform is arranged to move vertically toward and away from the underside of the wafer support member, and wherein said at least three pins are arranged to be moved through ~~vertical through~~ vertical-through holes, which extend from the underside of the wafer support member to the wafer bearing area, by said lifting platform in direct engagement to the pins, said pins being moveable between a first upper position wherein said pins project from the wafer bearing area by a selected amount and a second lower position wherein said pins are retracted into said through holes, wherein a separate pin guide body is provided for each pin, in which pin guide body the pin is guided and held for longitudinal movement, ~~and~~ wherein the pin guides body ~~are fixedly~~ is detachably connected to the wafer support member, wherein the pin guide has a guide hole in which the pin is arranged in movable fashion, and wherein the pin guide is arranged to hold the pin in said second lower position when the lifting platform is lowered.